imall

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NOT RECOMMENDED FOR NEW DESIGN **USE MJD32CUQ**



Lead-free Gr

MJD32CQ

100V PNP HIGH VOLTAGE TRANSISTOR IN TO252

Description

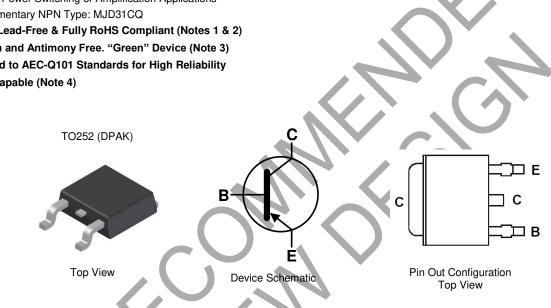
This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

Features

- $BV_{CEO} > -100V$
- I_C = -3A high Continuous Collector Current
- I_{CM} = -5A Peak Pulse Current
- Ideal for Power Switching or Amplification Applications
- Complementary NPN Type: MJD31CQ
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: TO252 (DPAK) •
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.34 grams (Approximate)



Ordering Information (Notes 4 & 5

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MJD32CQ-13	Automotive	MJD32C	13 16		2,500

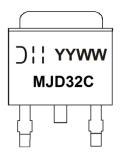
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/quality/product_compliance_definitions/. 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



MJD32C = Product Type Marking Code ⊃¦¦ = Manufacturers' code marking YYWW = Date Code Marking YY = Last Digit of Year (ex: 16 = 2016)WW = Week Code (01 - 53)



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Collector-Base Voltage	V _{CBO}	-100	V	
Collector-Emitter Voltage	V _{CEO}	-100	V	
Emitter-Base Voltage	V _{EBO}	-6	V	
Continuous Collector Current	lc	-3	А	
Peak Pulse Collector Current	I _{CM}	-5	A	
Continuous Base Current	IB	-1	А	
Power Dissipation	PD	15	W	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
	(Note 6)		3.9	
Power Dissipation	(Note 7)	PD	2.1	W
	(Note 8)		1.6	
	(Note 6)		32	
Thermal Resistance, Junction to Ambient Air	(Note 7)	Reja	59	°C/W
	(Note 8)		80	°C/W
Thermal Resistance, Junction to Leads	(Note 9)	R _{ejl}	8.4	
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C	

ESD Ratings (Note 10)

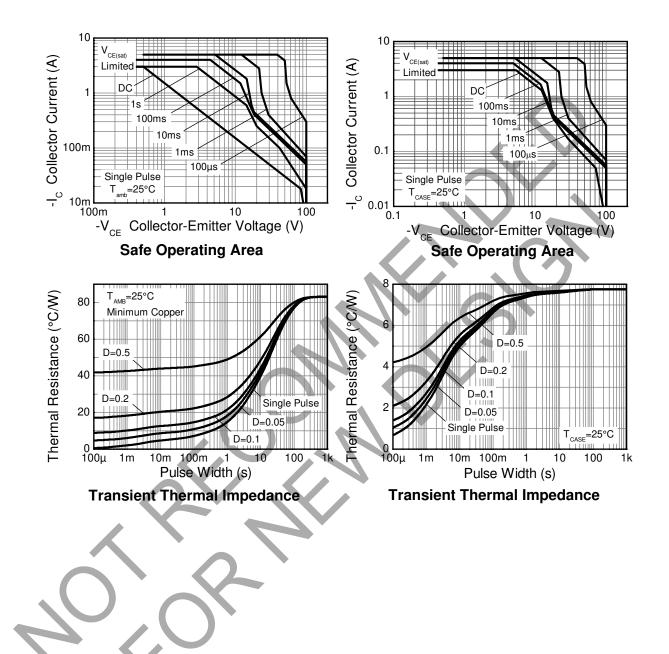
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

6. For a device mounted with the exposed collector pad on 50mm × 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
7. Same as note (6), except mounted on 25mm 1oz copper.
8. Same as note (6), except mounted on minimum recommended pad (MRP) layout.
9. Thermal resistance from junction to solder-point (on the exposed collector pad).
10. Refer to JEDEC specification JESD22-A114 and JESD22-A115. Notes:











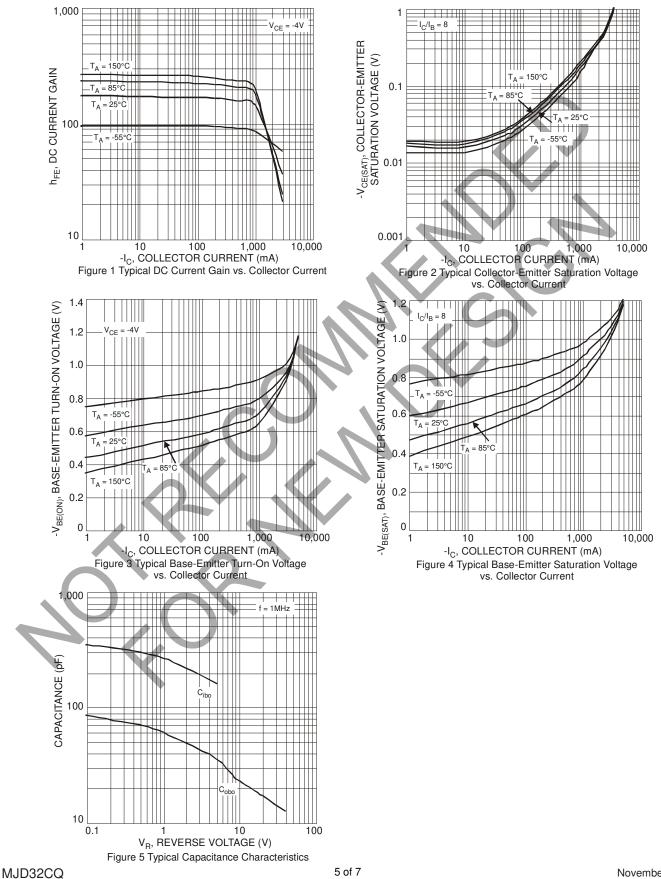
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Emitter Breakdown Voltage (Note 11)	BV _{CEO}	-100			V	$I_{\rm C} = -30 {\rm mA}, I_{\rm B} = 0$
Collector Cut-off Current	ICEO	_	_	-1	μA	$V_{CB} = -60V, I_B = 0$
Collector Cut-off Current	I _{CES}		_	-1	μA	$V_{CE} = -100V, V_{EB} = 0$
Emitter Cut-off Current	I _{EBO}	_	—	-1	μA	$V_{EB} = -5V, I_{C} = 0$
Collector-Emitter Saturation Voltage (Note 11)	V _{CE(sat)}	_	—	-1.2	V	I _C = -3.0A, I _B = -375mA
Base-Emitter Turn-On Voltage (Note 11)	V _{BE(on)}		—	-1.8	V	$I_{C} = -3A, V_{CE} = -4V$
DC Current Gain (Note 11)	h	25				$V_{CE} = -4V, I_{C} = -1A$
	h _{FE}	10	_	50		$V_{CE} = -4V, I_{C} = -3A$
Current Signal Current Gain	H _{fe}	20	_			V _{CE} = -10V, I _C = -0.5A, f = 1KHz
Current Gain-Bandwidth Product	fT	3.0			MHz	Ic = -500mA, V _{CE} = -10V, f = 1MHz

Note: 11. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



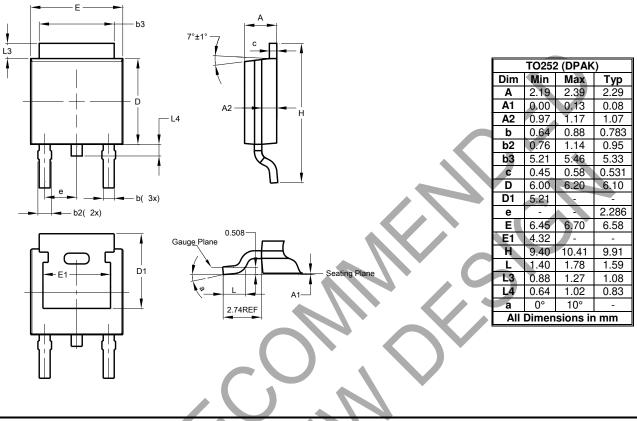
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)





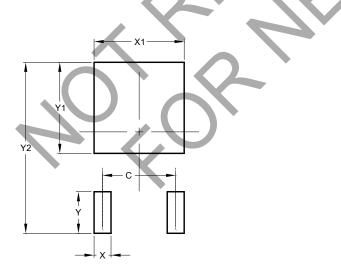
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	4.572
Х	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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